

# Bill of Materials

TI DESIGNS

TIDA-00534

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	!PCB		Printed Circuit Board	Any	TIDA-00534	
2	1	C1	10uF	CAP, CERM, 10 $\mu$ F, 10 V, +/-	TDK	C1608X5R1A106M	0603
3	2	C2, C3	100uF	CAP, CERM, 100 $\mu$ F, 6.3 V, +/- 20%, X5R, 1210	Kemet	C1210C107M9PACTU	1210
4	5	EN, GND, GND, VIN, VOUT	Double	Terminal, Turret, TH, Double	Keystone	1573-2	Keystone1573-2
5	2	GND		Standard Banana Jack, Insulated, Black	Keystone	6092	6092
6	2	J1, J3		Connector, TH, SMA	Emerson Network Powe	142-0701-201	SMA
7	1	J2		Header, 100mil, 3x1, TH	Mill-Max	800-10-003-10-001000	Header, 3x1,
8	1	R1	1.0k	RES, 1.0 k, 5%, 0.1 W, 0603	Vishay-Dale	CRCW06031K00JNEA	0603
9	1	U1		1A Low Dropout CMOS Linear	Texas Instruments	LP38692SD-3.3/NOPB	SDE06A
10	2	VIN, VOUT		Standard Banana Jack, Insulated, Red	Keystone	6091	6091
11	0	FID1, FID2, FID3		Fiducial mark. There is nothing to	N/A	N/A	Fiducial

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